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Applications of "<u>Embedded - Microcontrollers</u>"

| Details | |
|----------------------------|--|
| Product Status | Active |
| Core Processor | ARM® Cortex®-M0+ |
| Core Size | 32-Bit Single-Core |
| Speed | 24MHz |
| Connectivity | I ² C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART |
| Peripherals | Brown-out Detect/Reset, CapSense, LCD, LVD, POR, PWM, WDT |
| Number of I/O | 21 |
| Program Memory Size | 16KB (16K x 8) |
| Program Memory Type | FLASH |
| EEPROM Size | - |
| RAM Size | 2K x 8 |
| Voltage - Supply (Vcc/Vdd) | 1.71V ~ 5.5V |
| Data Converters | A/D 1x10b |
| Oscillator Type | Internal |
| Operating Temperature | -40°C ~ 85°C (TA) |
| Mounting Type | Surface Mount |
| Package / Case | 25-XFBGA, WLCSP |
| Supplier Device Package | 25-WLCSP (2.02x1.93) |
| Purchase URL | https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4024fni-s412t |



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Functional Definition

CPU and Memory Subsystem

CPU

The Cortex-M0+ CPU in the PSoC 4000S is part of the 32-bit MCU subsystem, which is optimized for low-power operation with extensive clock gating. Most instructions are 16 bits in length and the CPU executes a subset of the Thumb-2 instruction set. It includes a nested vectored interrupt controller (NVIC) block with eight interrupt inputs and also includes a Wakeup Interrupt Controller (WIC). The WIC can wake the processor from Deep Sleep mode, allowing power to be switched off to the main processor when the chip is in Deep Sleep mode.

The CPU also includes a debug interface, the serial wire debug (SWD) interface, which is a two-wire form of JTAG. The debug configuration used for PSoC 4000S has four breakpoint (address) comparators and two watchpoint (data) comparators.

Flash

The PSoC 4000S device has a flash module with a flash accelerator, tightly coupled to the CPU to improve average access times from the flash block. The low-power flash block is designed to deliver two wait-state (WS) access time at 48 MHz. The flash accelerator delivers 85% of single-cycle SRAM access performance on average.

SRAM

Four KB of SRAM are provided with zero wait-state access at 48 MHz.

SROM

A supervisory ROM that contains boot and configuration routines is provided.

System Resources

Power System

The power system is described in detail in the section Power on page 10. It provides assurance that voltage levels are as required for each respective mode and either delays mode entry (for example, on power-on reset (POR)) until voltage levels are as required for proper functionality, or generates resets (for example, on brown-out detection). The PSoC 4000S operates with a single external supply over the range of either 1.8 V $\pm 5\%$ (externally regulated) or 1.8 to 5.5 V (internally regulated) and has three different power modes, transitions between which are managed by the power system. The PSoC 4000S provides Active, Sleep, and Deep Sleep low-power modes.

All subsystems are operational in Active mode. The CPU subsystem (CPU, flash, and SRAM) is clock-gated off in Sleep mode, while all peripherals and interrupts are active with instantaneous wake-up on a wake-up event. In Deep Sleep mode, the high-speed clock and associated circuitry is switched off; wake-up from this mode takes 35 µs. The opamps can remain operational in Deep Sleep mode.

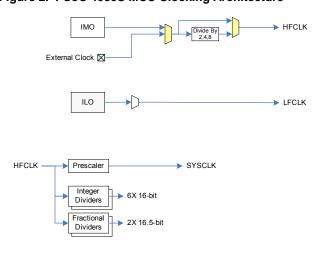
Clock System

The PSoC 4000S clock system is responsible for providing clocks to all subsystems that require clocks and for switching between different clock sources without glitching. In addition, the clock system ensures that there are no metastable conditions.

The clock system for the PSoC 4000S consists of the internal main oscillator (IMO), internal low-frequency oscillator (ILO), a 32 kHz Watch Crystal Oscillator (WCO) and provision for an external clock. Clock dividers are provided to generate clocks for peripherals on a fine-grained basis. Fractional dividers are also provided to enable clocking of higher data rates for UARTs.

The HFCLK signal can be divided down to generate synchronous clocks for the analog and digital peripherals. There are eight clock dividers for the PSoC 4000S, two of those are fractional dividers. The 16-bit capability allows flexible generation of fine-grained frequency values, and is fully supported in PSoC Creator.

Figure 2. PSoC 4000S MCU Clocking Architecture



IMO Clock Source

The IMO is the primary source of internal clocking in the PSoC 4000S. It is trimmed during testing to achieve the specified accuracy. The IMO default frequency is 24 MHz and it can be adjusted from 24 to 48 MHz in steps of 4 MHz. The IMO tolerance with Cypress-provided calibration settings is $\pm 2\%$.

ILO Clock Source

The ILO is a very low power, nominally 40-kHz oscillator, which is primarily used to generate clocks for the watchdog timer (WDT) and peripheral operation in Deep Sleep mode. ILO-driven counters can be calibrated to the IMO to improve accuracy. Cypress provides a software component, which does the calibration.

Watch Crystal Oscillator (WCO)

The PSoC 4000S clock subsystem also implements a low-frequency (32-kHz watch crystal) oscillator that can be used for precision timing applications.



Watchdog Timer

A watchdog timer is implemented in the clock block running from the ILO; this allows watchdog operation during Deep Sleep and generates a watchdog reset if not serviced before the set timeout occurs. The watchdog reset is recorded in a Reset Cause register, which is firmware readable.

Reset

The PSoC 4000S can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the reset. An XRES pin is reserved for external reset by asserting it active low. The XRES pin has an internal pull-up resistor that is always enabled.

Voltage Reference

The PSoC 4000S reference system generates all internally required references. A 1.2-V voltage reference is provided for the comparator. The IDACs are based on a ±5% reference.

Analog Blocks

Low-power Comparators (LPC)

The PSoC 4000S has a pair of low-power comparators, which can also operate in Deep Sleep modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode where the system wake-up circuit is activated by a comparator switch event. The LPC outputs can be routed to pins.

Current DACs

The PSoC 4000S has two IDACs, which can drive any of the pins on the chip. These IDACs have programmable current ranges.

Analog Multiplexed Buses

The PSoC 4000S has two concentric independent buses that go around the periphery of the chip. These buses (called amux buses) are connected to firmware-programmable analog switches that allow the chip's internal resources (IDACs, comparator) to connect to any pin on the I/O Ports.

Programmable Digital Blocks

The programmable I/O (Smart I/O) block is a fabric of switches and LUTs that allows Boolean functions to be performed in signals being routed to the pins of a GPIO port. The Smart I/O can perform logical operations on input pins to the chip and on signals going out as outputs.

Fixed Function Digital

Timer/Counter/PWM (TCPWM) Block

The TCPWM block consists of a 16-bit counter with user-programmable period length. There is a capture register to record the count value at the time of an event (which may be an I/O event), a period register that is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals that are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as dead-band programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an over-current state is indicated and the PWM driving the FETs needs to be shut off immediately with no time for software intervention. There are five TCPWM blocks in the PSoC 4000S.

Serial Communication Block (SCB)

The PSoC 4000S has two serial communication blocks, which can be programmed to have SPI, I2C, or UART functionality.

I²C Mode: The hardware I²C block implements a full multi-master and slave interface (it is capable of multi-master arbitration). This block is capable of operating at speeds of up to 400 kbps (Fast Mode) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. It also supports EZI2C that creates a mailbox address range in the memory of the PSoC 4000S and effectively reduces I²C communication to reading from and writing to an array in memory. In addition, the block supports an 8-deep FIFO for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduces the need for clock stretching caused by the CPU not having read data on time.

The I²C peripheral is compatible with the I²C Standard-mode and Fast-mode devices as defined in the NXP I²C-bus specification and user manual (UM10204). The I²C bus I/O is implemented with GPIO in open-drain modes.

The PSoC 4000S is not completely compliant with the I²C spec in the following respect:

■ GPIO cells are not overvoltage tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I²C system.

UART Mode: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

SPI Mode: The SPI mode supports full Motorola SPI, TI SSP (adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO.



GPIO

The PSoC 4000S has up to 36 GPIOs. The GPIO block implements the following:

- Eight drive modes:
- ☐ Analog input mode (input and output buffers disabled)
- □ Input only
- □ Weak pull-up with strong pull-down
- ☐ Strong pull-up with weak pull-down
- ☐ Open drain with strong pull-down
- □ Open drain with strong pull-up
- ☐ Strong pull-up with strong pull-down
- □ Weak pull-up with weak pull-down
- Input threshold select (CMOS or LVTTL).
- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes
- Selectable slew rates for dV/dt related noise control to improve EMI

The pins are organized in logical entities called ports, which are 8-bit in width (less for Ports 2 and 3). During power-on and reset, the blocks are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin.

Data output and pin state registers store, respectively, the values to be driven on the pins and the states of the pins themselves.

Every I/O pin can generate an interrupt if so enabled and each I/O port has an interrupt request (IRQ) and interrupt service routine (ISR) vector associated with it (5 for PSoC 4000S).

Special Function Peripherals

CapSense

CapSense is supported in the PSoC 4000S through a CapSense Sigma-Delta (CSD) block that can be connected to any pins through an analog multiplex bus via analog switches. CapSense function can thus be provided on any available pin or group of pins in a system under software control. A PSoC Creator component is provided for the CapSense block to make it easy for the user.

Shield voltage can be driven on another analog multiplex bus to provide water-tolerance capability. Water tolerance is provided by driving the shield electrode in phase with the sense electrode to keep the shield capacitance from attenuating the sensed input. Proximity sensing can also be implemented.

The CapSense block has two IDACs, which can be used for general purposes if CapSense is not being used (both IDACs are available in that case) or if CapSense is used without water tolerance (one IDAC is available).

The CapSense block also provides a 10-bit Slope ADC function, which can be used in conjunction with the CapSense function.

The CapSense block is an advanced, low-noise, programmable block with programmable voltage references and current source ranges for improved sensitivity and flexibility. It can also use an external reference voltage. It has a full-wave CSD mode that alternates sensing to VDDA and Ground to null out power-supply related noise.

LCD Segment Drive

The PSoC 4000S has an LCD controller, which can drive up to 8 commons and up to 28 segments. It uses full digital methods to drive the LCD segments requiring no generation of internal LCD voltages. The two methods used are referred to as Digital Correlation and PWM. Digital Correlation pertains to modulating the frequency and drive levels of the common and segment signals to generate the highest RMS voltage across a segment to light it up or to keep the RMS signal to zero. This method is good for STN displays but may result in reduced contrast with TN (cheaper) displays. PWM pertains to driving the panel with PWM signals to effectively use the capacitance of the panel to provide the integration of the modulated pulse-width to generate the desired LCD voltage. This method results in higher power consumption but can result in better results when driving TN displays. LCD operation is supported during Deep Sleep refreshing a small display buffer (4 bits; 1 32-bit register per port).



Table 1. PSoC 4000S Pin List (continued)

| 48 | -TQFP | 32 | 2-QFN | 2 | 4-QFN | 2 | 5-CSP | | 40-QFN |
|-----|-------|-----|-------|-----|-------|-----|-------|-----|--------|
| Pin | Name |
| 17 | P3.4 | | | | | | | 14 | P3.4 |
| 18 | P3.5 | | | | | | | 15 | P3.5 |
| 19 | P3.6 | | | | | | | 16 | P3.6 |
| 20 | P3.7 | | | | | | | 17 | P3.7 |
| 21 | VDDD | | | | | | | | |
| 22 | P4.0 | 13 | P4.0 | 9 | P4.0 | E3 | P4.0 | 18 | P4.0 |
| 23 | P4.1 | 14 | P4.1 | 10 | P4.1 | D2 | P4.1 | 19 | P4.1 |
| 24 | P4.2 | 15 | P4.2 | 11 | P4.2 | E2 | P4.2 | 20 | P4.2 |
| 25 | P4.3 | 16 | P4.3 | 12 | P4.3 | E1 | P4.3 | 21 | P4.3 |

Descriptions of the Pin functions are as follows:

VDDD: Power supply for the digital section.

VDDA: Power supply for the analog section.

VSSD, VSSA: Ground pins for the digital and analog sections respectively.

VCCD: Regulated digital supply (1.8 V ±5%)

VDD: Power supply to all sections of the chip

VSS: Ground for all sections of the chip

Alternate Pin Functions

Each port pin can be assigned to one of multiple functions; it can, for instance, be an analog I/O, a digital peripheral function, an LCD pin, or a CapSense pin. The pin assignments are shown in the following table.

| Port/ Pin | Analog | Smart I/O | Alternate Function 1 | Alternate Function 2 | Alternate Function 3 | Deep Sleep 1 | Deep Sleep 2 |
|--------------|----------------|-----------|-----------------------|----------------------|----------------------|------------------|----------------------|
| P0.0 | lpcomp.in_p[0] | | | | tcpwm.tr_in[0] | | scb[0].spi_select1:0 |
| P0.1 | lpcomp.in_n[0] | | | | tcpwm.tr_in[1] | | scb[0].spi_select2:0 |
| P0.2 | lpcomp.in_p[1] | | | | | | scb[0].spi_select3:0 |
| P0.3 | lpcomp.in_n[1] | | | | | | |
| P0.4 | wco.wco_in | | | scb[1].uart_rx:0 | | scb[1].i2c_scl:0 | scb[1].spi_mosi:1 |
| P0.5 | wco.wco_out | | | scb[1].uart_tx:0 | | scb[1].i2c_sda:0 | scb[1].spi_miso:1 |
| P0.6 | | | srss.ext_clk | scb[1].uart_cts:0 | | | scb[1].spi_clk:1 |
| P0.7 | | | | scb[1].uart_rts:0 | | | scb[1].spi_select0:1 |
| P1.0 | | | tcpwm.line[2]:1 | scb[0].uart_rx:1 | | scb[0].i2c_scl:0 | scb[0].spi_mosi:1 |
| P1.1 | | | tcpwm.line_compl[2]:1 | scb[0].uart_tx:1 | | scb[0].i2c_sda:0 | scb[0].spi_miso:1 |
| P1.2 | | | tcpwm.line[3]:1 | scb[0].uart_cts:1 | tcpwm.tr_in[2] | | scb[0].spi_clk:1 |
| P1.3 | | | tcpwm.line_compl[3]:1 | scb[0].uart_rts:1 | tcpwm.tr_in[3] | | scb[0].spi_select0:1 |
| P1.4 | | | | | | | scb[0].spi_select1:1 |
| P1.5 | | | | | | | scb[0].spi_select2:1 |

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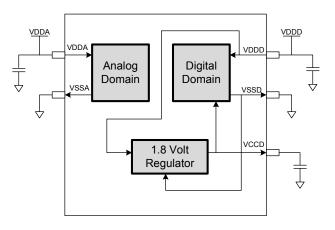
| Port/ Pin | Analog | Smart I/O | Alternate Function 1 | Alternate Function 2 | Alternate Function 3 | Deep Sleep 1 | Deep Sleep 2 |
|--------------|-----------------|----------------|-----------------------|----------------------|----------------------|------------------|----------------------|
| P1.6 | | | | | | | scb[0].spi_select3:1 |
| P1.7 | | | | | | | |
| P2.0 | | prgio[0].io[0] | tcpwm.line[4]:0 | csd.comp | tcpwm.tr_in[4] | scb[1].i2c_scl:1 | scb[1].spi_mosi:2 |
| | | | | | | | |
| P2.1 | | prgio[0].io[1] | tcpwm.line_compl[4]:0 | | tcpwm.tr_in[5] | scb[1].i2c_sda:1 | scb[1].spi_miso:2 |
| P2.2 | | prgio[0].io[2] | | | | | scb[1].spi_clk:2 |
| P2.3 | | prgio[0].io[3] | | | | | scb[1].spi_select0:2 |
| P2.4 | | prgio[0].io[4] | tcpwm.line[0]:1 | | | | scb[1].spi_select1:1 |
| P2.5 | | prgio[0].io[5] | tcpwm.line_compl[0]:1 | | | | scb[1].spi_select2:1 |
| P2.6 | | prgio[0].io[6] | tcpwm.line[1]:1 | | | | scb[1].spi_select3:1 |
| P2.7 | | prgio[0].io[7] | tcpwm.line_compl[1]:1 | | | lpcomp.comp[0]:1 | |
| P3.0 | | prgio[1].io[0] | tcpwm.line[0]:0 | scb[1].uart_rx:1 | | scb[1].i2c_scl:2 | scb[1].spi_mosi:0 |
| P3.1 | | prgio[1].io[1] | tcpwm.line_compl[0]:0 | scb[1].uart_tx:1 | | scb[1].i2c_sda:2 | scb[1].spi_miso:0 |
| P3.2 | | prgio[1].io[2] | tcpwm.line[1]:0 | scb[1].uart_cts:1 | | cpuss.swd_data | scb[1].spi_clk:0 |
| P3.3 | | prgio[1].io[3] | tcpwm.line_compl[1]:0 | scb[1].uart_rts:1 | | cpuss.swd_clk | scb[1].spi_select0:0 |
| P3.4 | | prgio[1].io[4] | tcpwm.line[2]:0 | | tcpwm.tr_in[6] | | scb[1].spi_select1:0 |
| P3.5 | | prgio[1].io[5] | tcpwm.line_compl[2]:0 | | tcpwm.tr_in[7] | | scb[1].spi_select2:0 |
| P3.6 | | prgio[1].io[6] | tcpwm.line[3]:0 | | tcpwm.tr_in[8] | | scb[1].spi_select3:0 |
| P3.7 | | prgio[1].io[7] | tcpwm.line_compl[3]:0 | | tcpwm.tr_in[9] | lpcomp.comp[1]:1 | |
| P4.0 | csd.vref_ext | | | scb[0].uart_rx:0 | tcpwm.tr_in[10] | scb[0].i2c_scl:1 | scb[0].spi_mosi:0 |
| P4.1 | csd.cshieldpads | | | scb[0].uart_tx:0 | tcpwm.tr_in[11] | scb[0].i2c_sda:1 | scb[0].spi_miso:0 |
| P4.2 | csd.cmodpad | | | scb[0].uart_cts:0 | | lpcomp.comp[0]:0 | scb[0].spi_clk:0 |
| P4.3 | csd.csh_tank | | | scb[0].uart_rts:0 | | lpcomp.comp[1]:0 | scb[0].spi_select0:0 |
| | | | | | | | |



Power

The following power system diagram shows the set of power supply pins as implemented for the PSoC 4000S. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the V_{DD} input.

Figure 3. Power Supply Connections



There are two distinct modes of operation. In Mode 1, the supply voltage range is 1.8 V to 5.5 V (unregulated externally; internal regulator operational). In Mode 2, the supply range is $1.8 \text{ V} \pm 5\%$ (externally regulated; 1.71 to 1.89, internal regulator bypassed).

Mode 1: 1.8 V to 5.5 V External Supply

In this mode, the PSoC 4000S is powered by an external power supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation. For example, the chip can be powered from a battery system that starts at 3.5 V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4000S supplies the internal logic and its output is connected to the V_{CCD} pin. The VCCD pin must be bypassed to ground via an external capacitor (0.1 $\mu F;\, X5R$ ceramic or better) and must not be connected to anything else.

Mode 2: 1.8 V ±5% External Supply

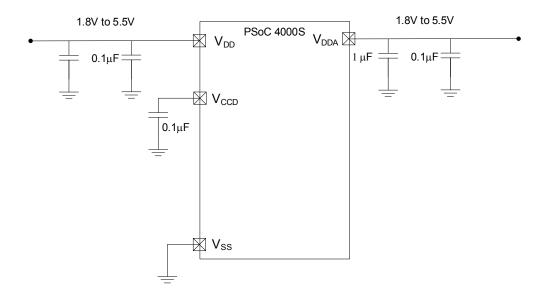
In this mode, the PSoC 4000S is powered by an external power supply that must be within the range of 1.71 to 1.89 V; note that this range needs to include the power supply ripple too. In this mode, the VDD and VCCD pins are shorted together and bypassed. The internal regulator can be disabled in the firmware.

Bypass capacitors must be used from VDDD to ground. The typical practice for systems in this frequency range is to use a capacitor in the 1- μ F range, in parallel with a smaller capacitor (0.1 μ F, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

An example of a bypass scheme is shown in the following diagram.

Figure 4. External Supply Range from 1.8 V to 5.5 V with Internal Regulator Active

Power supply bypass connections example





GPIO

Table 5. GPIO DC Specifications

| Spec ID# | Parameter | Description | Min | Тур | Max | Units | Details/ Conditions |
|-----------------------|--------------------------------|---|-------------------------|-----|----------------------|-------|---|
| SID57 | V _{IH} ^[3] | Input voltage high threshold | $0.7 \times V_{DDD}$ | - | - | | CMOS Input |
| SID58 | V _{IL} | Input voltage low threshold | - | _ | $0.3 \times V_{DDD}$ | | CMOS Input |
| SID241 | V _{IH} ^[3] | LVTTL input, V _{DDD} < 2.7 V | $0.7 \times V_{DDD}$ | - | _ | | _ |
| SID242 | V _{IL} | LVTTL input, V _{DDD} < 2.7 V | - | _ | $0.3 \times V_{DDD}$ | | _ |
| SID243 | V _{IH} [3] | LVTTL input, $V_{DDD} \ge 2.7 \text{ V}$ | 2.0 | - | _ |] ,, | _ |
| SID244 | V_{IL} | LVTTL input, $V_{DDD} \ge 2.7 \text{ V}$ | _ | - | 8.0 | V | _ |
| SID59 | V _{OH} | Output voltage high level | V _{DDD} -0.6 | - | _ | | I_{OH} = 4 mA at 3 V V_{DDD} |
| SID60 | V _{OH} | Output voltage high level | V _{DDD} -0.5 | - | _ | | I_{OH} = 1 mA at 3 V V_{DDD} |
| SID61 | V _{OL} | Output voltage low level | - | _ | 0.6 | | I _{OL} = 4 mA at 1.8 V V _{DDD} |
| SID62 | V_{OL} | Output voltage low level | _ | - | 0.6 | | I_{OL} = 10 mA at 3 V V_{DDD} |
| SID62A | V_{OL} | Output voltage low level | _ | - | 0.4 | | I_{OL} = 3 mA at 3 V V_{DDD} |
| SID63 | R _{PULLUP} | Pull-up resistor | 3.5 | 5.6 | 8.5 | kΩ | _ |
| SID64 | R _{PULLDOWN} | Pull-down resistor | 3.5 | 5.6 | 8.5 | N22 | _ |
| SID65 | I _{IL} | Input leakage current (absolute value) | - | _ | 2 | nA | 25 °C, V _{DDD} = 3.0 V |
| SID66 | C _{IN} | Input capacitance | _ | - | 7 | pF | _ |
| SID67 ^[4] | V _{HYSTTL} | Input hysteresis LVTTL | 25 | 40 | _ | | $V_{DDD} \ge 2.7 \text{ V}$ |
| SID68 ^[4] | V _{HYSCMOS} | Input hysteresis CMOS | 0.05 × V _{DDD} | - | _ | mV | V _{DD} < 4.5 V |
| SID68A ^[4] | V _{HYSCMOS5V5} | Input hysteresis CMOS | 200 | - | _ | | V _{DD} > 4.5 V |
| SID69 ^[4] | I _{DIODE} | Current through protection diode to V_{DD}/V_{SS} | - | _ | 100 | μA | - |
| SID69A ^[4] | I _{TOT_GPIO} | Maximum total source or sink chip current | _ | _ | 200 | mA | _ |

Table 6. GPIO AC Specifications

(Guaranteed by Characterization)

| Spec ID# | Parameter | Description | Min | Тур | Max | Units | Details/ Conditions |
|----------|--------------------|-------------------------------|-----|-----|-----|-------|--|
| SID70 | T _{RISEF} | Rise time in fast strong mode | 2 | _ | 12 | ns - | 3.3 V V _{DDD} , Cload = 25 pF |
| SID71 | T _{FALLF} | Fall time in fast strong mode | 2 | - | 12 | | 3.3 V V _{DDD} , Cload = 25 pF |
| SID72 | T _{RISES} | Rise time in slow strong mode | 10 | - | 60 | _ | 3.3 V V _{DDD} , Cload = 25 pF |
| SID73 | T _{FALLS} | Fall time in slow strong mode | 10 | _ | 60 | _ | 3.3 V V _{DDD} , Cload = 25 pF |

V_{IH} must not exceed V_{DDD} + 0.2 V.
 Guaranteed by characterization.



Table 11. CSD and IDAC Specifications (continued)

| SPEC ID# | Parameter | Description | Min | Тур | Max | Units | Details / Conditions |
|----------|---------------|--|-----|-----|-----|-------|---|
| SID315G | IDAC3CRT23 | Output current of IDAC in 8-bit mode in medium range | 69 | _ | 82 | μA | LSB = 300-nA typ. |
| SID315H | IDAC3CRT33 | Output current of IDAC in 8-bit mode in high range | 540 | _ | 660 | μA | LSB = 2.4-µA typ. |
| SID320 | IDACOFFSET | All zeroes input | - | - | 1 | LSB | Polarity set by Source or Sink. Offset is 2 LSBs for 37.5 nA/LSB mode |
| SID321 | IDACGAIN | Full-scale error less offset | - | _ | ±10 | % | |
| SID322 | IDACMISMATCH1 | Mismatch between IDAC1 and IDAC2 in Low mode | - | - | 9.2 | LSB | LSB = 37.5-nA typ. |
| SID322A | IDACMISMATCH2 | Mismatch between IDAC1 and IDAC2 in Medium mode | - | - | 5.6 | LSB | LSB = 300-nA typ. |
| SID322B | IDACMISMATCH3 | Mismatch between IDAC1 and IDAC2 in High mode | - | - | 6.8 | LSB | LSB = 2.4-µA typ. |
| SID323 | IDACSET8 | Settling time to 0.5 LSB for 8-bit IDAC | - | - | 10 | μs | Full-scale transition. No external load. |
| SID324 | IDACSET7 | Settling time to 0.5 LSB for 7-bit IDAC | _ | - | 10 | μs | Full-scale transition. No external load. |
| SID325 | CMOD | External modulator capacitor. | - | 2.2 | _ | nF | 5-V rating, X7R or NP0 cap. |

Table 12. 10-bit CapSense ADC Specifications

| Spec ID# | Parameter | Description | Min | Тур | Max | Units | Details/Conditions |
|----------|-----------|---|-----------|-----|-----------|-------|--|
| SIDA94 | A_RES | Resolution | _ | _ | 10 | bits | Auto-zeroing is required every millisecond |
| SIDA95 | A_CHNLS_S | Number of channels - single ended | _ | - | 16 | | Defined by AMUX Bus. |
| SIDA97 | A-MONO | Monotonicity | - | _ | _ | Yes | |
| SIDA98 | A_GAINERR | Gain error | - | _ | ±2 | % | In V _{REF} (2.4 V) mode with V _{DDA} bypass capac- itance of 10 µF |
| SIDA99 | A_OFFSET | Input offset voltage | - | - | 3 | mV | In V _{REF} (2.4 V) mode with V _{DDA} bypass capac- itance of 10 µF |
| SIDA100 | A_ISAR | Current consumption | - | _ | 0.25 | mA | |
| SIDA101 | A_VINS | Input voltage range - single ended | V_{SSA} | - | V_{DDA} | V | |
| SIDA103 | A_INRES | Input resistance | - | 2.2 | _ | ΚΩ | |
| SIDA104 | A_INCAP | Input capacitance | - | 20 | _ | pF | |
| SIDA106 | A_PSRR | Power supply rejection ratio | - | 60 | - | dB | In V _{REF} (2.4 V) mode with V _{DDA} bypass capac- itance of 10 µF |
| SIDA107 | A_TACQ | Sample acquisition time | - | 1 | _ | μs | |
| SIDA108 | A_CONV8 | Conversion time for 8-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz. | - | _ | 21.3 | μs | Does not include acquisition time. Equivalent to 44.8 ksps including acquisition time. |
| SIDA108A | A_CONV10 | Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz. | - | - | 85.3 | μs | Does not include acquisition time. Equivalent to 11.6 ksps including acquisition time. |

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 Table 12. 10-bit CapSense ADC Specifications (continued)

| Spec ID# | Parameter | Description | Min | Тур | Max | Units | Details/Conditions |
|----------|-----------|--|-----|-----|------|-------|--|
| SIDA109 | A_SND | Signal-to-noise and Distortion ratio (SINAD) | - | 61 | - | dB | With 10-Hz input sine wave, external 2.4-V reference, V _{REF} (2.4 V) mode |
| SIDA110 | A_BW | Input bandwidth without aliasing | _ | _ | 22.4 | kHz | 8-bit resolution |
| SIDA111 | A_INL | Integral Non Linearity. 1 ksps | _ | _ | 2 | LSB | V _{REF} = 2.4 V or greater |
| SIDA112 | A_DNL | Differential Non Linearity. 1 ksps | _ | _ | 1 | LSB | |

Digital Peripherals

Timer Counter Pulse-Width Modulator (TCPWM)

Table 13. TCPWM Specifications

| Spec ID | Parameter | Description | Min | Тур | Max | Units | Details/Conditions |
|--------------|-----------------------|-------------------------------------|------|-----|-----|-------|---|
| SID.TCPWM.1 | ITCPWM1 | Block current consumption at 3 MHz | - | _ | 45 | | All modes (TCPWM) |
| SID.TCPWM.2 | ITCPWM2 | Block current consumption at 12 MHz | - | _ | 155 | μΑ | All modes (TCPWM) |
| SID.TCPWM.2A | ITCPWM3 | Block current consumption at 48 MHz | - | _ | 650 | | All modes (TCPWM) |
| SID.TCPWM.3 | TCPWM _{FREQ} | Operating frequency | - | - | Fc | MHz | Fc max = CLK_SYS Maximum = 48 MHz |
| SID.TCPWM.4 | TPWM _{ENEXT} | Input trigger pulse width | 2/Fc | _ | - | | For all trigger events ^[6] |
| SID.TCPWM.5 | TPWM _{EXT} | Output trigger pulse widths | 2/Fc | 1 | ı | | Minimum possible width of Overflow, Underflow, and CC (Counter equals Compare value) outputs |
| SID.TCPWM.5A | TC _{RES} | Resolution of counter | 1/Fc | - | _ | ns | Minimum time between successive counts |
| SID.TCPWM.5B | PWM _{RES} | PWM resolution | 1/Fc | - | - | | Minimum pulse width of PWM Output |
| SID.TCPWM.5C | Q _{RES} | Quadrature inputs resolution | 1/Fc | _ | - | | Minimum pulse width between Quadrature phase inputs |

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Note
6. Trigger events can be Stop, Start, Reload, Count, Capture, or Kill depending on which mode of operation is selected.



Memory

Table 22. Flash DC Specifications

| Spec ID | Parameter | Description | Min | Тур | Max | Units | Details/Conditions |
|---------|-----------|---------------------------|------|-----|-----|-------|--------------------|
| SID173 | V_{PE} | Erase and program voltage | 1.71 | 1 | 5.5 | V | _ |

Table 23. Flash AC Specifications

| Spec ID | Parameter | Description | Min | Тур | Max | Units | Details/Conditions | |
|-------------------------|--|--|-------|-----|-----|---------|--------------------------|--|
| SID174 | T _{ROWWRITE} ^[9] | Row (block) write time (erase and program) | - | _ | 20 | | Row (block) = 128 bytes | |
| SID175 | T _{ROWERASE} ^[9] | Row erase time | - | - | 16 | ms | _ | |
| SID176 | T _{ROWPROGRAM} ^[9] | Row program time after erase | - | _ | 4 | | - | |
| SID178 | T _{BULKERASE} ^[9] | Bulk erase time (32 KB) | - | - | 35 | | _ | |
| SID180 ^[10] | T _{DEVPROG} ^[9] | Total device program time | _ | - | 7 | Seconds | _ | |
| SID181 ^[10] | F _{END} | Flash endurance | 100 K | - | _ | Cycles | _ | |
| SID182 ^[10] | F _{RET} | Flash retention. $T_A \le 55$ °C, 100 K P/E cycles | 20 | - | _ | - Years | _ | |
| SID182A ^[10] | _ | Flash retention. $T_A \le 85$ °C, 10 K P/E cycles | 10 | - | _ | Tears | _ | |
| SID256 | TWS48 | Number of Wait states at 48 MHz | 2 | - | _ | | CPU execution from Flash | |
| SID257 | TWS24 | Number of Wait states at 24 MHz | | - | _ | | CPU execution from Flash | |

System Resources

Power-on Reset (POR)

Table 24. Power On Reset (PRES)

| Spec ID | Parameter | Description | Min | Тур | Max | Units | Details/Conditions |
|------------------------|-----------------------|------------------------|------|-----|-----|-------|--------------------|
| SID.CLK#6 | SR_POWER_UP | Power supply slew rate | 1 | 1 | 67 | V/ms | At power-up |
| SID185 ^[10] | V _{RISEIPOR} | Rising trip voltage | 0.80 | 1 | 1.5 | V | _ |
| SID186 ^[10] | V _{FALLIPOR} | Falling trip voltage | 0.70 | - | 1.4 | | _ |

Table 25. Brown-out Detect (BOD) for $V_{\mbox{\scriptsize CCD}}$

| Spec ID | Parameter | Description | Min | Тур | Max | Units | Details/Conditions |
|------------------------|------------------------|--|------|-----|------|-------|--------------------|
| SID190 ^[10] | V _{FALLPPOR} | BOD trip voltage in active and sleep modes | 1.48 | 1 | 1.62 | V | - |
| SID192 ^[10] | V _{FALLDPSLP} | BOD trip voltage in Deep Sleep | 1.11 | ı | 1.5 | | - |

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Notes

9. It can take as much as 20 milliseconds to write to Flash. During this time the device should not be Reset, or Flash operations will be interrupted and cannot be relied on to have completed. Reset sources include the XRES pin, software resets, CPU lockup states and privilege violations, improper power supply levels, and watchdogs. Make certain that these are not inadvertently activated.



SWD Interface

Table 26. SWD Interface Specifications

| Spec ID | Parameter | Description | Min | Тур | Max | Units | Details/Conditions |
|-------------------------|--------------|--|-----------|-------|-----|-------|----------------------------------|
| SID213 | F_SWDCLK1 | $3.3~V \leq V_{DD} \leq 5.5~V$ | - 1 | | 14 | MHz | SWDCLK ≤ 1/3 CPU clock frequency |
| SID214 | F_SWDCLK2 | $1.71 \text{ V} \le \text{V}_{DD} \le 3.3 \text{ V}$ | _ | ı | 7 | | SWDCLK ≤ 1/3 CPU clock frequency |
| SID215 ^[11] | T_SWDI_SETUP | T = 1/f SWDCLK | 0.25*T | _ | _ | | _ |
| SID216 ^[11] | T_SWDI_HOLD | T = 1/f SWDCLK | 0.25*T | _ | _ | ns | _ |
| SID217 ^[11] | T_SWDO_VALID | T = 1/f SWDCLK | – – 0.5*T | | 115 | _ | |
| SID217A ^[11] | T_SWDO_HOLD | T = 1/f SWDCLK | 1 | 1 – - | | | _ |

Internal Main Oscillator

Table 27. IMO DC Specifications

(Guaranteed by Design)

| Spec ID | Parameter | Description | Min | Тур | Max | Units | Details/Conditions |
|---------|-------------------|---------------------------------|-----|-----|-----|-------|--------------------|
| SID218 | I _{IMO1} | IMO operating current at 48 MHz | | _ | 250 | μA | - |
| SID219 | I _{IMO2} | IMO operating current at 24 MHz | - | - | 180 | μΑ | _ |

Table 28. IMO AC Specifications

| Spec ID | Parameter | Description | Min | Тур | Max | Units | Details/Conditions |
|---------|-------------------------|---|-----|-----|-----|-------|--------------------|
| SID223 | F _{IMOTOL1} | Frequency variation at 24, 32, and 48 MHz (trimmed) | _ | _ | ±2 | % | |
| SID226 | T _{STARTIMO} | IMO startup time | _ | _ | 7 | μs | - |
| SID228 | T _{JITRMSIMO2} | RMS jitter at 24 MHz | _ | 145 | - | ps | _ |

Internal Low-Speed Oscillator

Table 29. ILO DC Specifications

(Guaranteed by Design)

| Spec ID | Parameter Description | | Min | Тур | Max | Units | Details/Conditions |
|------------------------|-----------------------|-----------------------|-----|-----|------|-------|--------------------|
| SID231 ^[11] | I _{ILO1} | ILO operating current | ı | 0.3 | 1.05 | μΑ | _ |

Table 30. ILO AC Specifications

| Spec ID | Parameter | Description | Min | Тур | Max | Units | Details/Conditions |
|------------------------|------------------------|---------------------|-----|-----|-----|-------|--------------------|
| SID234 ^[11] | T _{STARTILO1} | ILO startup time | _ | - | 2 | ms | _ |
| SID236 ^[11] | T _{ILODUTY} | ILO duty cycle | 40 | 50 | 60 | % | _ |
| SID237 | F _{ILOTRIM1} | ILO frequency range | 20 | 40 | 80 | kHz | _ |

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Note 11. Guaranteed by characterization.



Ordering Information

The PSoC 4000S part numbers and features are listed in the following table.

Table 35. PSoC 4000S Ordering Information

| | | | | | | | Feat | ures | | | | | | | P | ackaç | ge | |
|----------|------------------|---------------------|------------|-----------|--------------|----------|----------------|----------------|----------------|--------------|------------|------------|------|-----------------------|------------|------------|------------|-------------|
| Category | MPN | Max CPU Speed (MHz) | Flash (KB) | SRAM (KB) | Opamp (CTBm) | CapSense | 10-bit CSD ADC | 12-bit SAR ADC | LP Comparators | TCPWM Blocks | SCB Blocks | Smart I/Os | GPIO | WLCSP (0.35-mm pitch) | 24-Pin QFN | 32-Pin QFN | 40-Pin QFN | 48-Pin TQFP |
| | CY8C4024FNI-S402 | 24 | 16 | 2 | 0 | 0 | 1 | 0 | 2 | 5 | 2 | 8 | 21 | ~ | | | | |
| | CY8C4024LQI-S401 | 24 | 16 | 2 | 0 | 0 | 1 | 0 | 2 | 5 | 2 | 8 | 19 | | ~ | | | |
| | CY8C4024LQI-S402 | 24 | 16 | 2 | 0 | 0 | 1 | 0 | 2 | 5 | 2 | 16 | 27 | | | ~ | | |
| | CY8C4024LQI-S403 | 24 | 16 | 2 | 0 | 0 | 1 | 0 | 2 | 5 | 2 | 16 | 34 | | | | > | |
| 4024 | CY8C4024AZI-S403 | 24 | 16 | 2 | 0 | 0 | 1 | 0 | 2 | 5 | 2 | 16 | 36 | | | | | ~ |
| 4024 | CY8C4024FNI-S412 | 24 | 16 | 2 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 8 | 21 | ~ | | | | |
| | CY8C4024LQI-S411 | 24 | 16 | 2 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 8 | 19 | | ~ | | | |
| | CY8C4024LQI-S412 | 24 | 16 | 2 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 16 | 27 | | | ~ | | |
| | CY8C4024LQI-S413 | 24 | 16 | 2 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 16 | 34 | | | | ~ | |
| | CY8C4024AZI-S413 | 24 | 16 | 2 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 16 | 36 | | | | | ~ |
| | CY8C4025FNI-S402 | 24 | 32 | 4 | 0 | 0 | 1 | 0 | 2 | 5 | 2 | 8 | 21 | ~ | | | | |
| | CY8C4025LQI-S401 | 24 | 32 | 4 | 0 | 0 | 1 | 0 | 2 | 5 | 2 | 8 | 19 | | ~ | | | |
| | CY8C4025LQI-S402 | 24 | 32 | 4 | 0 | 0 | 1 | 0 | 2 | 5 | 2 | 16 | 27 | | | ~ | | |
| 4025 | CY8C4025AZI-S403 | 24 | 32 | 4 | 0 | 0 | 1 | 0 | 2 | 5 | 2 | 16 | 36 | | | | | ~ |
| 4023 | CY8C4025FNI-S412 | 24 | 32 | 4 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 8 | 21 | ~ | | | | |
| | CY8C4025LQI-S411 | 24 | 32 | 4 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 8 | 19 | | ~ | | | |
| | CY8C4025LQI-S412 | 24 | 32 | 4 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 16 | 27 | | | ~ | | |
| | CY8C4025AZI-S413 | 24 | 32 | 4 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 16 | 36 | | | | | ~ |
| | CY8C4045FNI-S412 | 48 | 32 | 4 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 8 | 21 | ~ | | | | |
| 4045 | CY8C4045LQI-S411 | 48 | 32 | 4 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 8 | 19 | | ~ | | | |
| 4040 | CY8C4045LQI-S412 | 48 | 32 | 4 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 16 | 27 | | | ~ | | |
| | CY8C4045AZI-S413 | 48 | 32 | 4 | 0 | 1 | 1 | 0 | 2 | 5 | 2 | 16 | 36 | | | | | ~ |

The nomenclature used in the preceding table is based on the following part numbering convention:

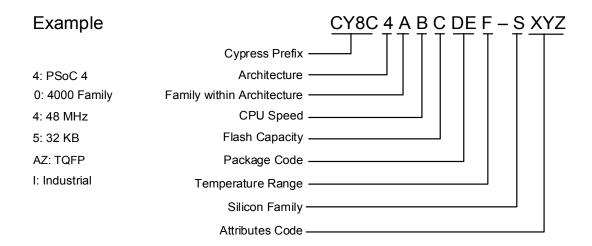
| Field | Description | Values | Meaning |
|-------|----------------|--------|-------------|
| CY8C | Cypress Prefix | | |
| 4 | Architecture | 4 | PSoC 4 |
| Α | Family | 0 | 4000 Family |
| В | CPU Speed | 2 | 24 MHz |
| | B OI O Opeca | | 48 MHz |

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| Field | Description | Values | Meaning | | | | |
|-------|-------------------|--------------|--|--------------|--------------|----|-----|
| | | 4 | 16 KB | | | | |
| С | Flash Capacity | 5 | 32 KB | | | | |
| | | 6 | 64 KB | | | | |
| | | 7 | 128 KB | | | | |
| | | AX | TQFP (0.8-mm pitch) | | | | |
| | | AZ | TQFP (0.5-mm pitch) | | | | |
| DE | Package Code | Package Code | Package Code | Package Code | Package Code | LQ | QFN |
| | | PV | SSOP | | | | |
| | | FN | CSP | | | | |
| F | Temperature Range | Ĺ | Industrial | | | | |
| | | S | PSoC 4A-S1, PSoC 4A-S2 | | | | |
| S | Silioon Family | М | PSoC 4A-M | | | | |
| 3 | Silicon Family —— | | PSoC 4A-L | | | | |
| | | BL | PSoC 4A-BLE | | | | |
| XYZ | Attributes Code | 000-999 | Code of feature set in the specific family | | | | |

The following is an example of a part number:





Packaging

The PSoC 4000S will be offered in 48-pin TQFP, 40-pin QFN, 32-pin QFN, 24-pin QFN, and 25-ball WLCSP packages. Package dimensions and Cypress drawing numbers are in the following table.

Table 36. Package List

| Spec ID# | Package | Description | Package Dwg |
|----------|---------------|---|-------------|
| BID20 | 48-pin TQFP | 7 × 7 × 1.4 mm height with 0.5-mm pitch | 51-85135 |
| BID27 | 40-pin QFN | 6 × 6 × 0.6 mm height with 0.5-mm pitch | 001-80659 |
| BID34A | 32-pin QFN | 5 × 5 × 0.6 mm height with 0.5-mm pitch | 001-42168 |
| BID34 | 24-pin QFN | 4 × 4 × 0.6 mm height with 0.5-mm pitch | 001-13937 |
| BID34F | 25-ball WLCSP | 2.02 × 1.93 × 0.48 mm height with 0.35-mm pitch | 002-09957 |

Table 37. Package Thermal Characteristics

| Parameter | Description | Package | Min | Тур | Max | Units |
|-----------|--------------------------------|---------------|-----|------|-----|---------|
| TA | Operating ambient temperature | | -40 | 25 | 85 | °C |
| TJ | Operating junction temperature | | -40 | _ | 100 | °C |
| TJA | Package θ _{JA} | 48-pin TQFP | - | 73.5 | _ | °C/Watt |
| TJC | Package θ _{JC} | 48-pin TQFP | - | 33.5 | _ | °C/Watt |
| TJA | Package θ _{JA} | 40-pin QFN | - | 17.8 | _ | °C/Watt |
| TJC | Package θ _{JC} | 40-pin QFN | - | 2.8 | _ | °C/Watt |
| TJA | Package θ _{JA} | 32-pin QFN | - | 20.8 | _ | °C/Watt |
| TJC | Package θ _{JC} | 32-pin QFN | - | 5.9 | _ | °C/Watt |
| TJA | Package θ _{JA} | 24-pin QFN | _ | 21.7 | _ | °C/Watt |
| TJC | Package θ_{JC} | 24-pin QFN | _ | 5.6 | _ | °C/Watt |
| TJA | Package θ _{JA} | 25-ball WLCSP | _ | 54.6 | _ | °C/Watt |
| TJC | Package θ _{JC} | 25-ball WLCSP | _ | 0.5 | _ | °C/Watt |

Table 38. Solder Reflow Peak Temperature

| Package | Maximum Peak Temperature | Maximum Time at Peak Temperature |
|---------|-----------------------------|----------------------------------|
| All | 260 °C | 30 seconds |

Table 39. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-020

| Package | MSL |
|------------------|-------|
| All except WLCSP | MSL 3 |
| 25-ball WLCSP | MSL 1 |

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Package Diagrams

Figure 5. 48-pin TQFP Package Outline

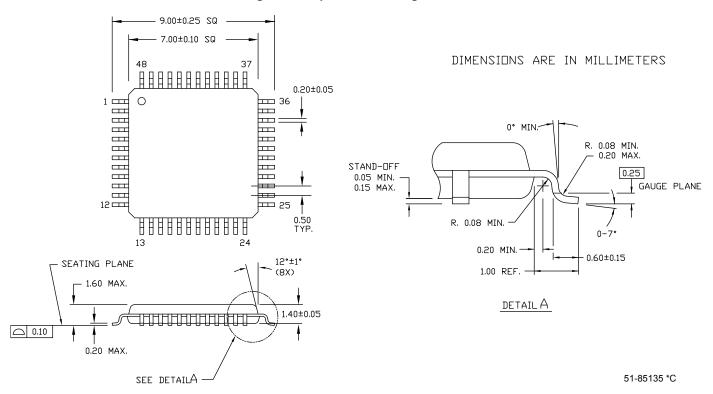
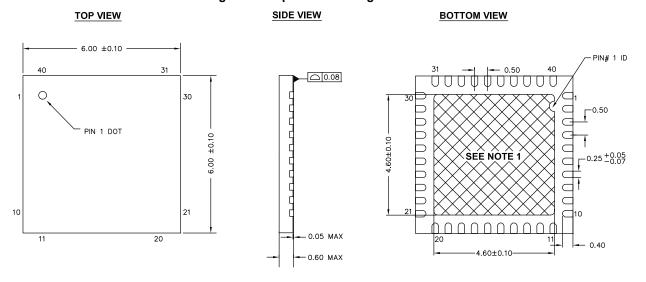


Figure 6. 40-pin QFN Package Outline



NOTES:

- 2. REFERENCE JEDEC # MO-248
- 3. PACKAGE WEIGHT: 68 ±2 mg
- 4. ALL DIMENSIONS ARE IN MILLIMETERS

001-80659 *A



Acronyms

Table 40. Acronyms Used in this Document

| Acronym | Description |
|------------------|---|
| abus | analog local bus |
| ADC | analog-to-digital converter |
| AG | analog global |
| АНВ | AMBA (advanced microcontroller bus architecture) high-performance bus, an ARM data transfer bus |
| ALU | arithmetic logic unit |
| AMUXBUS | analog multiplexer bus |
| API | application programming interface |
| APSR | application program status register |
| ARM [®] | advanced RISC machine, a CPU architecture |
| ATM | automatic thump mode |
| BW | bandwidth |
| CAN | Controller Area Network, a communications protocol |
| CMRR | common-mode rejection ratio |
| CPU | central processing unit |
| CRC | cyclic redundancy check, an error-checking protocol |
| DAC | digital-to-analog converter, see also IDAC, VDAC |
| DFB | digital filter block |
| DIO | digital input/output, GPIO with only digital capabilities, no analog. See GPIO. |
| DMIPS | Dhrystone million instructions per second |
| DMA | direct memory access, see also TD |
| DNL | differential nonlinearity, see also INL |
| DNU | do not use |
| DR | port write data registers |
| DSI | digital system interconnect |
| DWT | data watchpoint and trace |
| ECC | error correcting code |
| ECO | external crystal oscillator |
| EEPROM | electrically erasable programmable read-only memory |
| EMI | electromagnetic interference |
| EMIF | external memory interface |
| EOC | end of conversion |
| EOF | end of frame |
| EPSR | execution program status register |
| ESD | electrostatic discharge |

Table 40. Acronyms Used in this Document (continued)

| Acronym | Description | | |
|--------------------------|--|--|--|
| ETM | embedded trace macrocell | | |
| FIR | finite impulse response, see also IIR | | |
| FPB | flash patch and breakpoint | | |
| FS | full-speed | | |
| GPIO | general-purpose input/output, applies to a PSoC pin | | |
| HVI | high-voltage interrupt, see also LVI, LVD | | |
| IC | integrated circuit | | |
| IDAC | current DAC, see also DAC, VDAC | | |
| IDE | integrated development environment | | |
| I ² C, or IIC | Inter-Integrated Circuit, a communications protocol | | |
| IIR | infinite impulse response, see also FIR | | |
| ILO | internal low-speed oscillator, see also IMO | | |
| IMO | internal main oscillator, see also ILO | | |
| INL | integral nonlinearity, see also DNL | | |
| I/O | input/output, see also GPIO, DIO, SIO, USBIO | | |
| IPOR | initial power-on reset | | |
| IPSR | interrupt program status register | | |
| IRQ | interrupt request | | |
| ITM | instrumentation trace macrocell | | |
| LCD | liquid crystal display | | |
| LIN | Local Interconnect Network, a communications protocol. | | |
| LR | link register | | |
| LUT | lookup table | | |
| LVD | low-voltage detect, see also LVI | | |
| LVI | low-voltage interrupt, see also HVI | | |
| LVTTL | low-voltage transistor-transistor logic | | |
| MAC | multiply-accumulate | | |
| MCU | microcontroller unit | | |
| MISO | master-in slave-out | | |
| NC | no connect | | |
| NMI | nonmaskable interrupt | | |
| NRZ | non-return-to-zero | | |
| NVIC | nested vectored interrupt controller | | |
| NVL | nonvolatile latch, see also WOL | | |
| opamp | operational amplifier | | |
| PAL | programmable array logic, see also PLD | | |

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Document Conventions

Units of Measure

Table 41. Units of Measure

| Symbol | Unit of Measure | | |
|--------|------------------------|--|--|
| °C | degrees Celsius | | |
| dB | decibel | | |
| fF | femto farad | | |
| Hz | hertz | | |
| KB | 1024 bytes | | |
| kbps | kilobits per second | | |
| Khr | kilohour | | |
| kHz | kilohertz | | |
| kΩ | kilo ohm | | |
| ksps | kilosamples per second | | |
| LSB | least significant bit | | |
| Mbps | megabits per second | | |
| MHz | megahertz | | |
| ΜΩ | mega-ohm | | |
| Msps | megasamples per second | | |
| μΑ | microampere | | |
| μF | microfarad | | |
| μH | microhenry | | |
| μs | microsecond | | |
| μV | microvolt | | |
| μW | microwatt | | |
| mA | milliampere | | |
| ms | millisecond | | |
| mV | millivolt | | |
| nA | nanoampere | | |
| ns | nanosecond | | |
| nV | nanovolt | | |
| Ω | ohm | | |
| pF | picofarad | | |
| ppm | parts per million | | |
| ps | picosecond | | |
| S | second | | |
| sps | samples per second | | |
| sqrtHz | square root of hertz | | |
| V | volt | | |

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Revision History

| Revision | ECN | Orig. of Change | Submission Date | Description of Change |
|----------|---------|--------------------|--------------------|--|
| ** | 4883809 | WKA | 08/28/2015 | New datasheet |
| *A | 4992376 | WKA | 10/30/2015 | Updated Pinouts. Added $V_{DDD} \ge 2.2V$ at −40 °C under Conditions for specs SID247A, SID90, SID92. Updated Table 12. Updated Ordering Information. |
| *B | 5037826 | SLAN | 12/08/2015 | Changed datasheet status to Preliminary |
| *C | 5104369 | WKA | 01/27/2016 | Added Errata. Added 25 WLCSP package details. Updated theta J _A and J _C values for all packages. |
| *D | 5139206 | WKA | 02/16/2016 | Updated copyright information at the end of the document. |
| *E | 5173961 | WKA | 03/15/2016 | Updated Pinouts. Updated values for SID79, BID194. SID175, and SID176. Updated CSD and IDAC Specifications. Updated 10-bit CapSense ADC Specifications. |
| *F | 5268662 | WKA | 05/12/2016 | Updated Alternate Pin Functions. Updated the following specs: SID310, SID312, SID313, SID314, SID314C, SID314D, SID314E, SID315, SID315C, SID315D, SID315E, SID322A, SID322B, SIDA109. Removed Errata section. Updated the Cypress logo and copyright information based on the template. |
| *G | 5330930 | WKA | 07/27/2016 | Updated LCD Segment Drive. Updated SID60 conditions. Updated IDD specs. Corrected package dimensions for WLCSP package and added WLCSP MSL condition. Moved datasheet status to Final. |
| *H | 5415365 | WKA | 09/14/2016 | Added 40-pin QFN pin and package details. Updated IDD spec values in DC Specifications. |
| * | 5561833 | WKA | 01/09/2017 | Changed PRGIO references to Smart I/O. |
| *J | 5704046 | GNKK | 04/26/2017 | Updated the Cypress logo and copyright information. |

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